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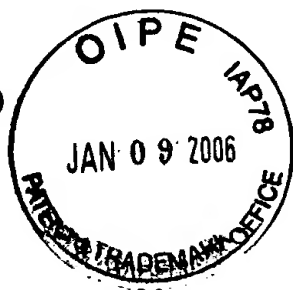
Applicant: Xiao-Chun Mu et al.

Title: Microelectronic Package Having an Integrated Heat Sink and Build-Up Layers

Docket No.: 884.798US1

Filed: December 8, 2000

Examiner: DiLinh Nguyen



Serial No.: 09/733,289

Due Date: January 5, 2006

Group Art Unit: 2814

MS AF

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

We are transmitting herewith the following attached items (as indicated with an "X"):

X Return postcard.

X Response Under 37 CFR 1.116 (16 pgs.).

X COPIES of Supplemental Information Disclosure Statement (2 pg.), Form 1449 (1 pg.), 4 cited non-U.S. patent documents, all previously filed July 24, 2003, and date-stamped itemized postcard from same (1 pg.).

If not provided for in a separate paper filed herewith, Please consider this a **PETITION FOR EXTENSION OF TIME** for sufficient number of months to enter these papers and please charge any additional fees or credit overpayment to Deposit Account No. 19-0743.

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